

Fig. 1A PRIOR ART

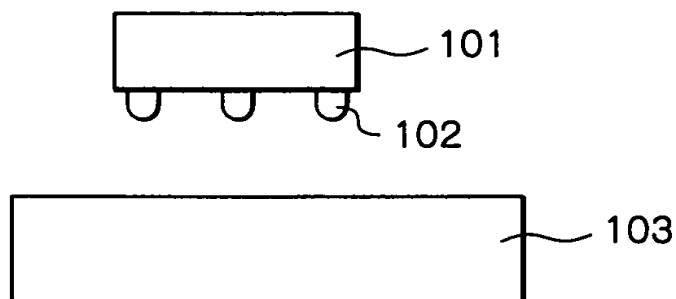


Fig. 1B PRIOR ART

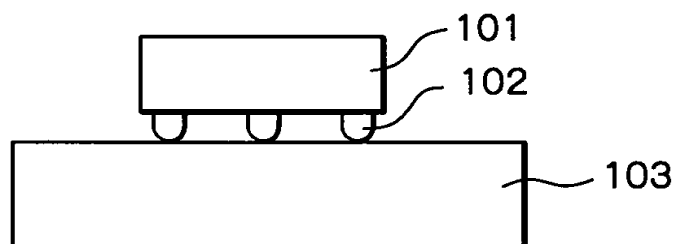


Fig. 1C PRIOR ART

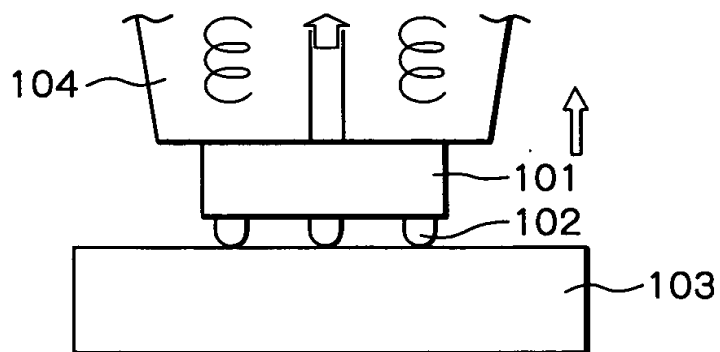


Fig. 2A

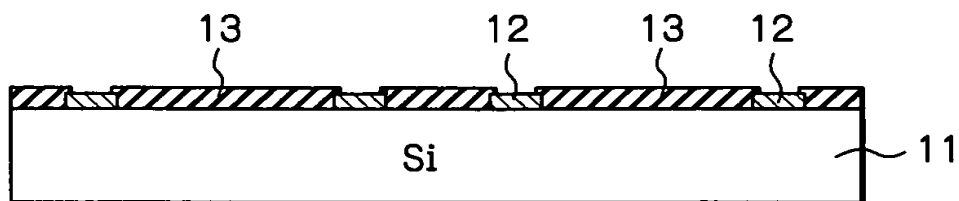


Fig. 2B

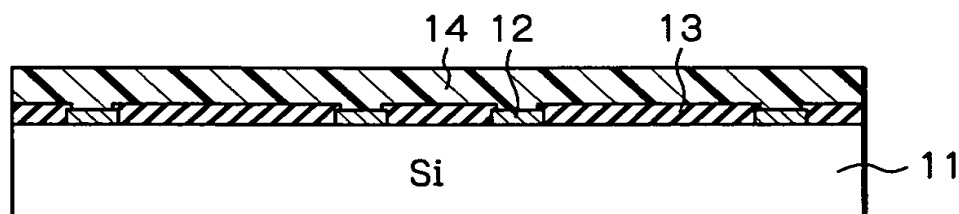


Fig. 2C

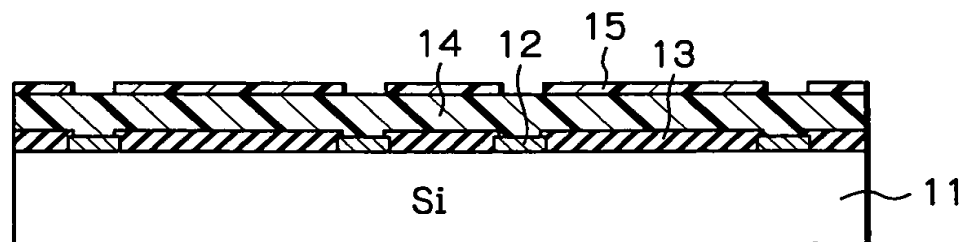


Fig. 2D

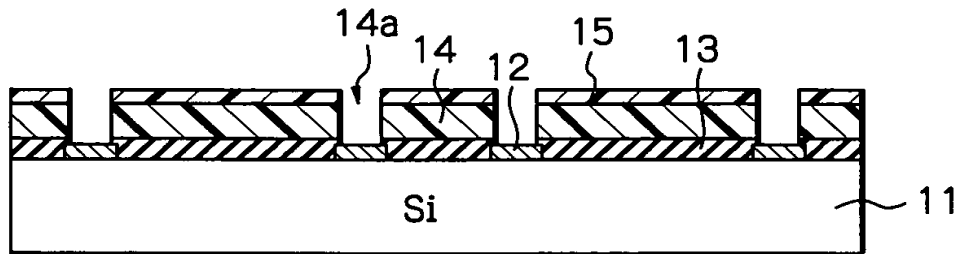


Fig. 2E

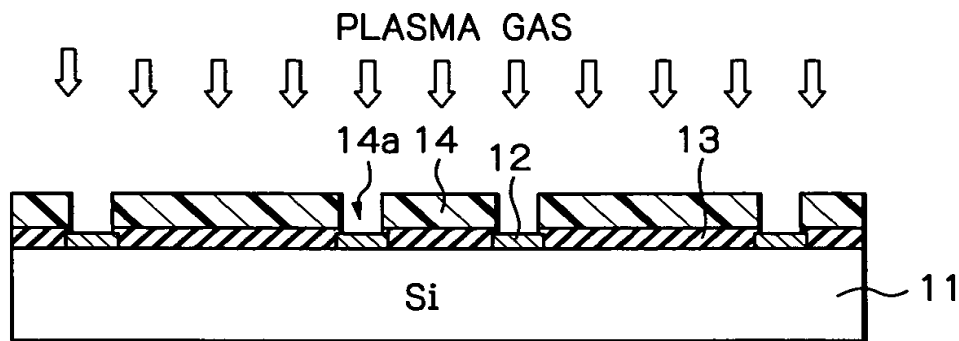


Fig. 2F

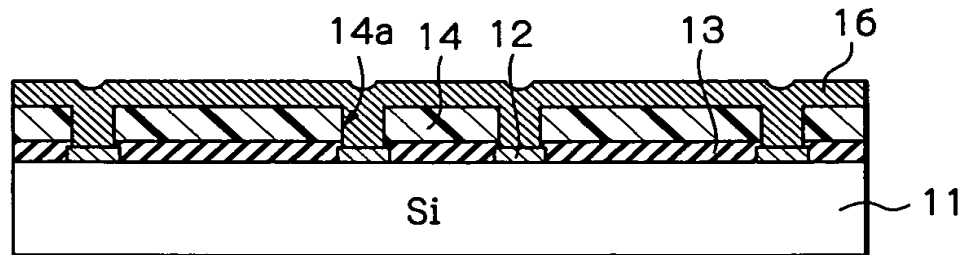


Fig. 2G

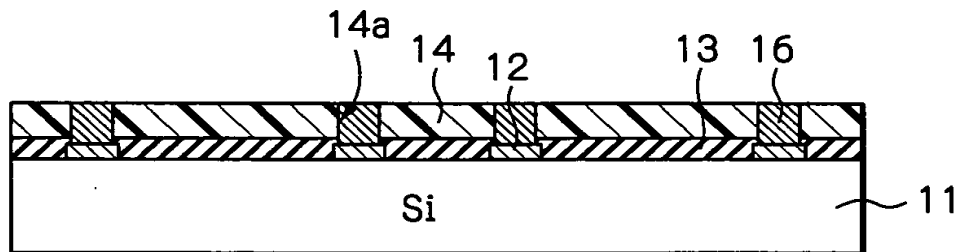


Fig. 2H

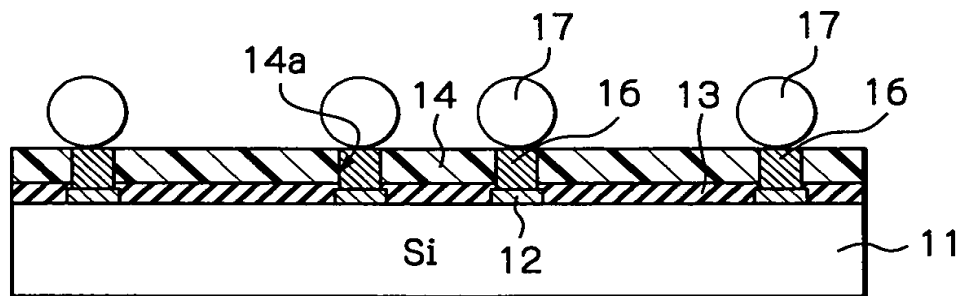


Fig. 2I

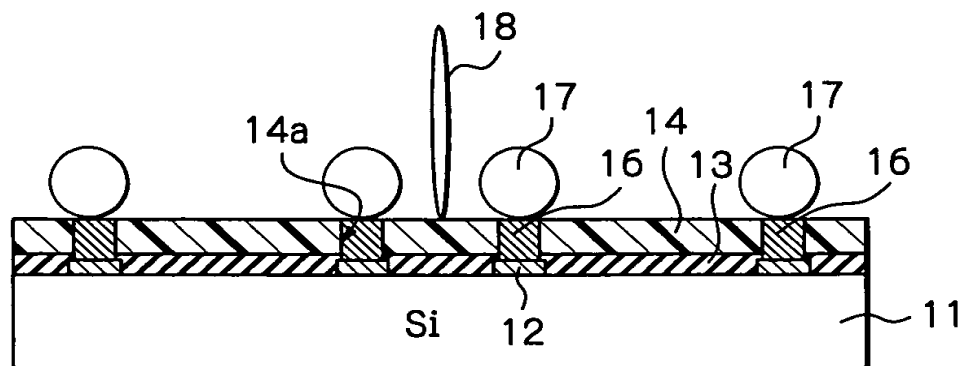


Fig. 2J

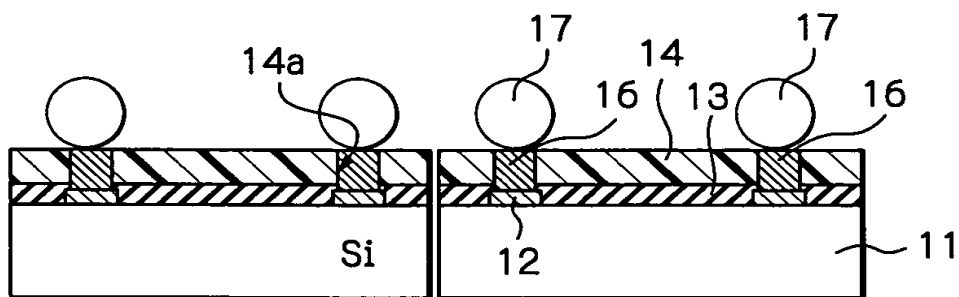
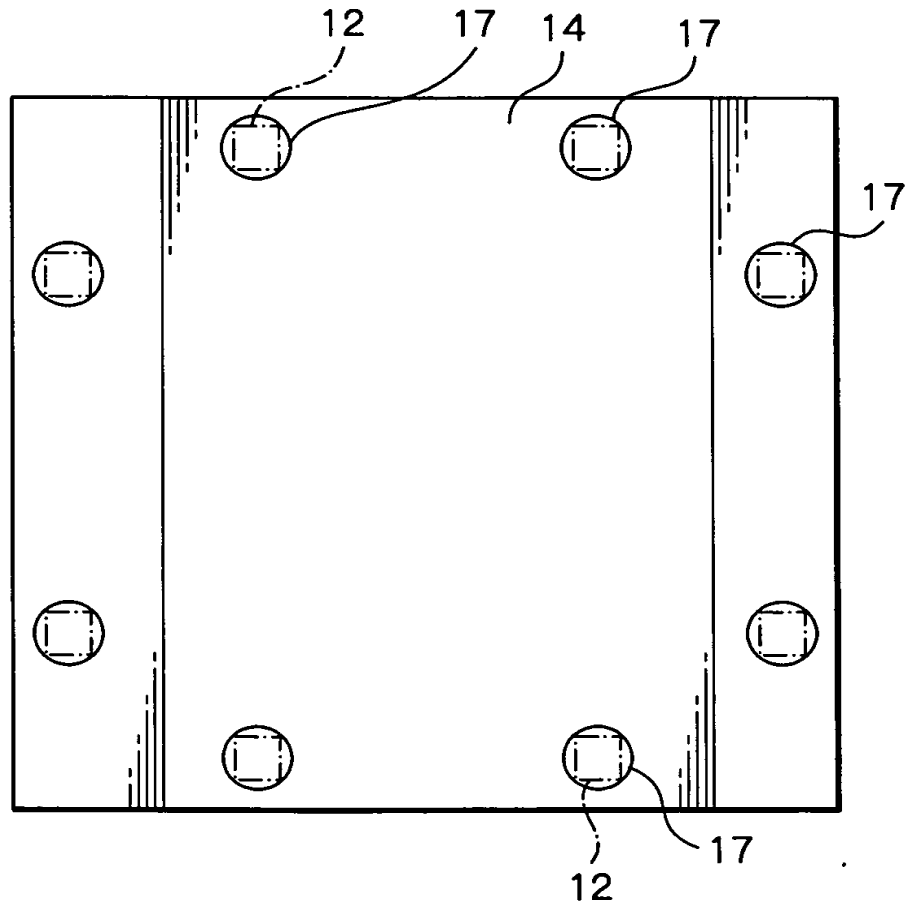


Fig. 3



Title: METHOD OF MANUFACTURING A
FLIP-CHIP SEMICONDUCTOR DEVICE
WITH A STRESS-ABSORBING LAYER
MADE OF THERMOSETTING RESIN

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Fig. 4

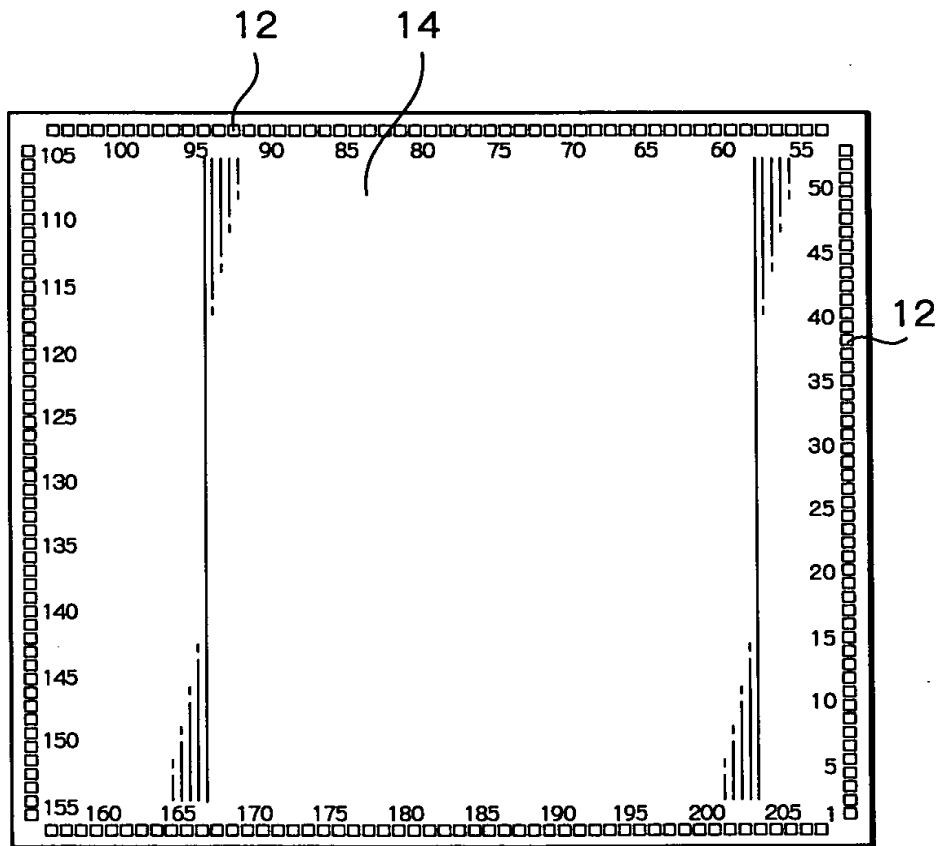


Fig. 5A

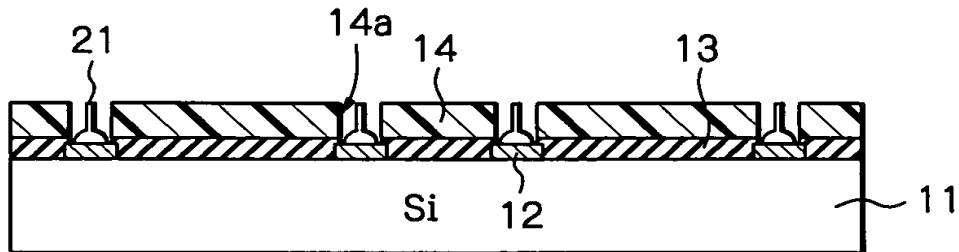


Fig. 5B

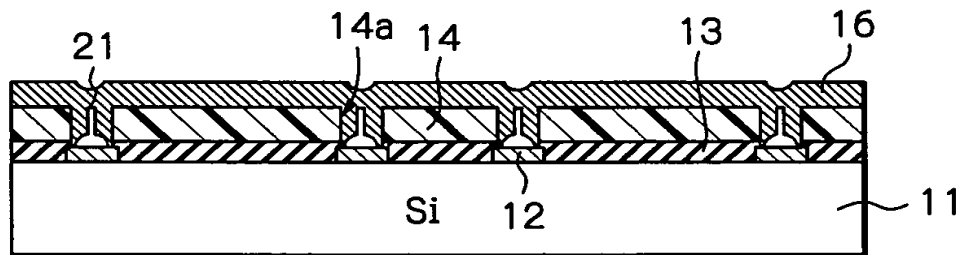


Fig. 5C

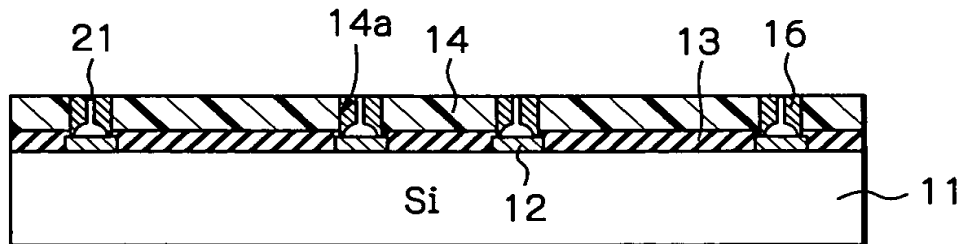


Fig. 5D

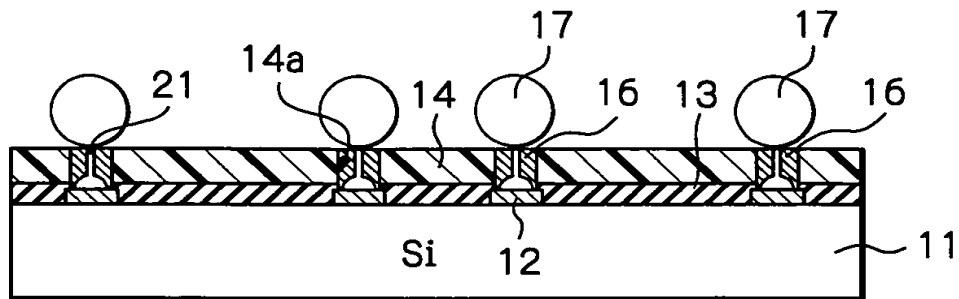


Fig. 5E

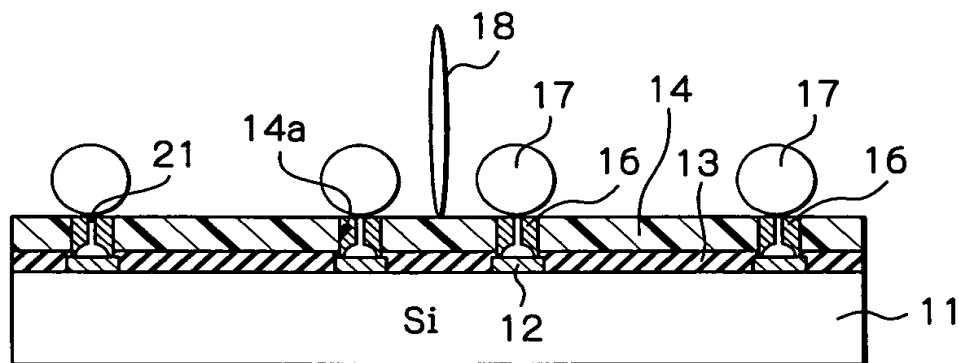


Fig. 5F

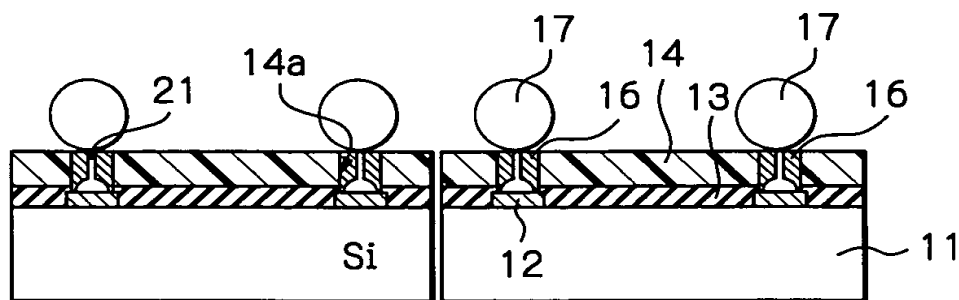


Fig. 6A

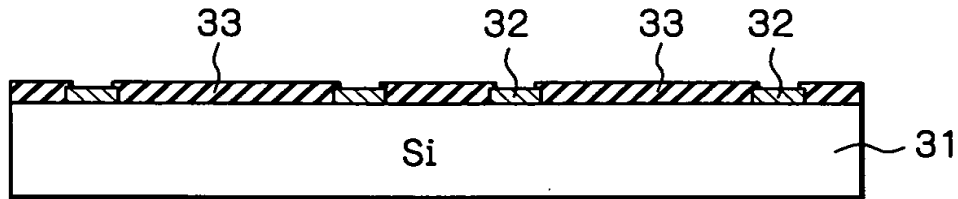


Fig. 6B

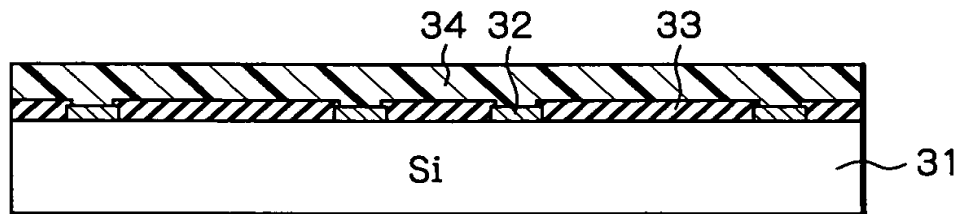


Fig. 6C

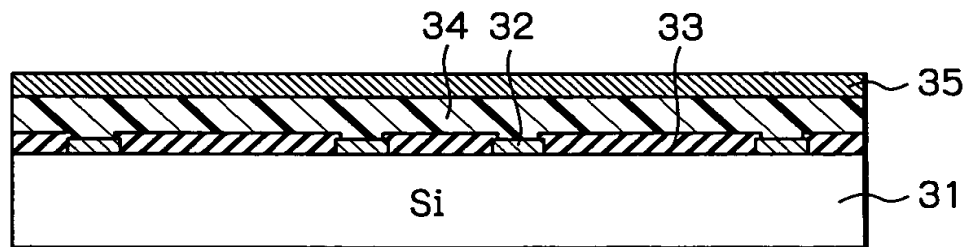


Fig. 6D

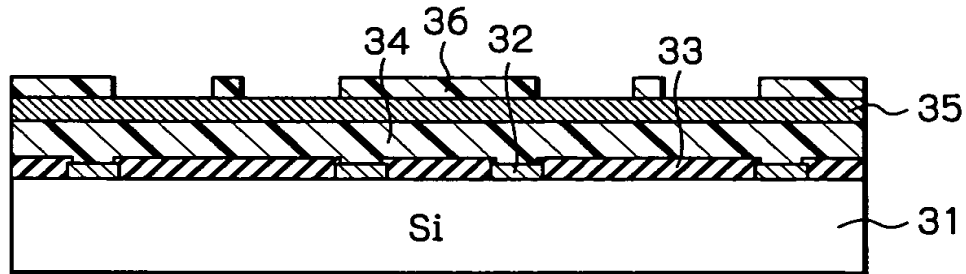


Fig. 6E

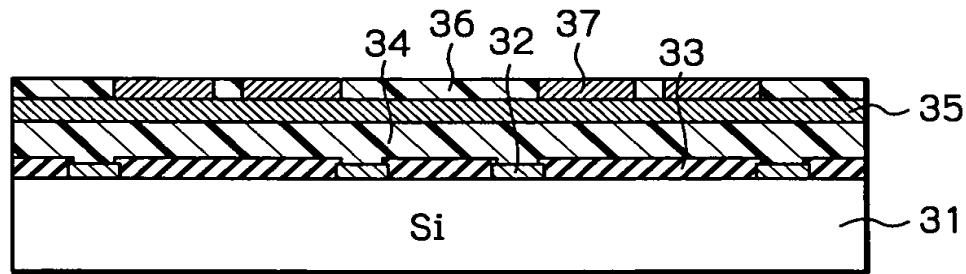


Fig. 6F

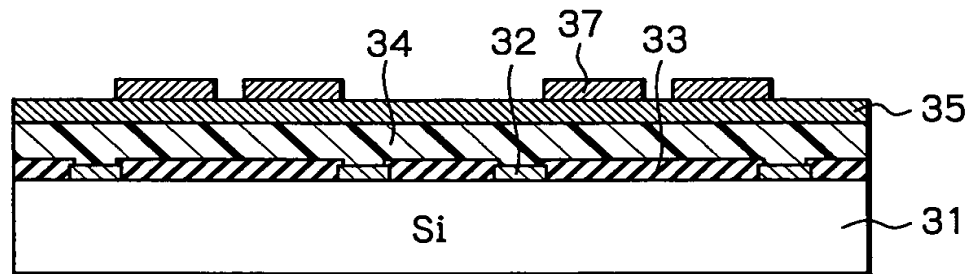


Fig. 6G

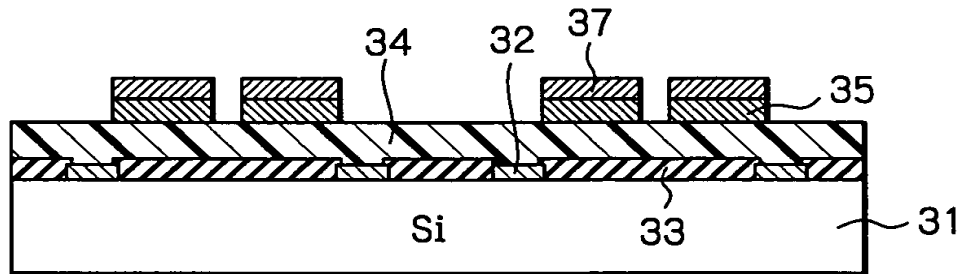


Fig. 6H

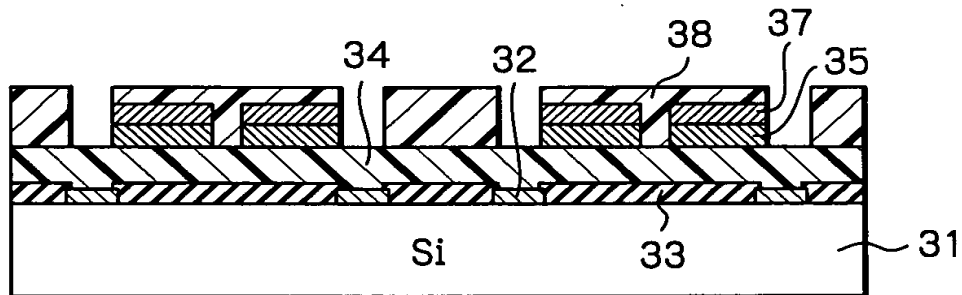


Fig. 6I

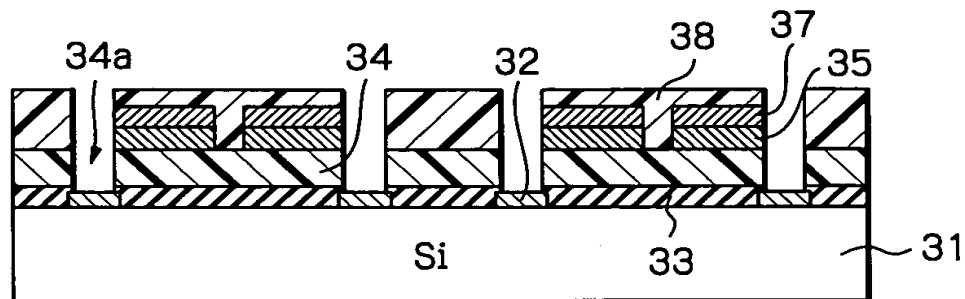


Fig. 6J

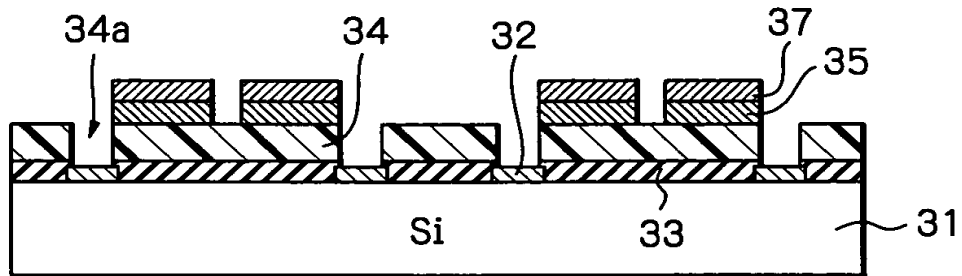


Fig. 6K

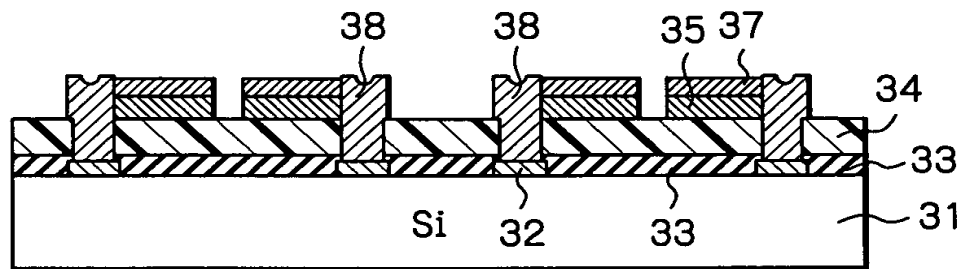


Fig. 6L

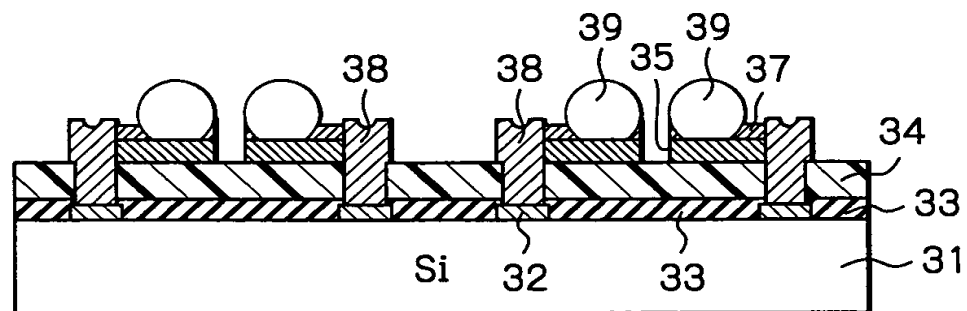


Fig. 6M

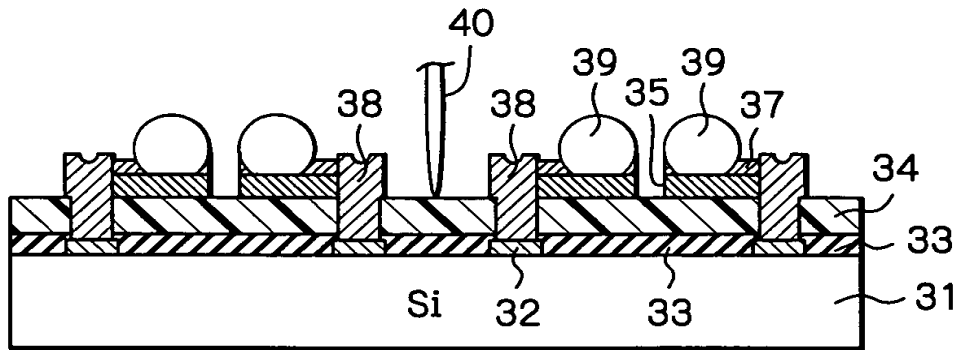


Fig. 6N

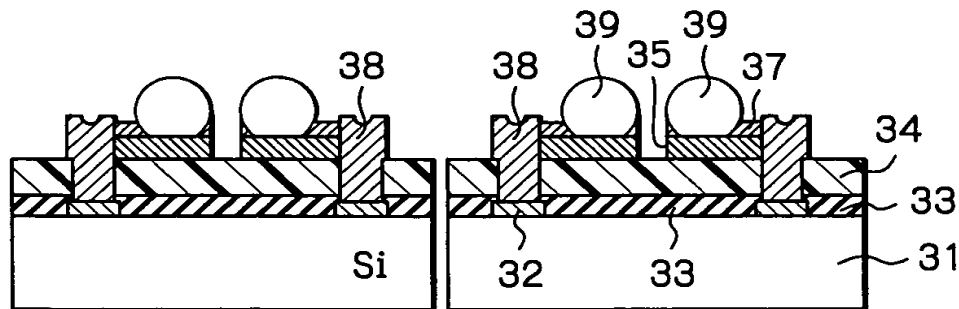


Fig. 7

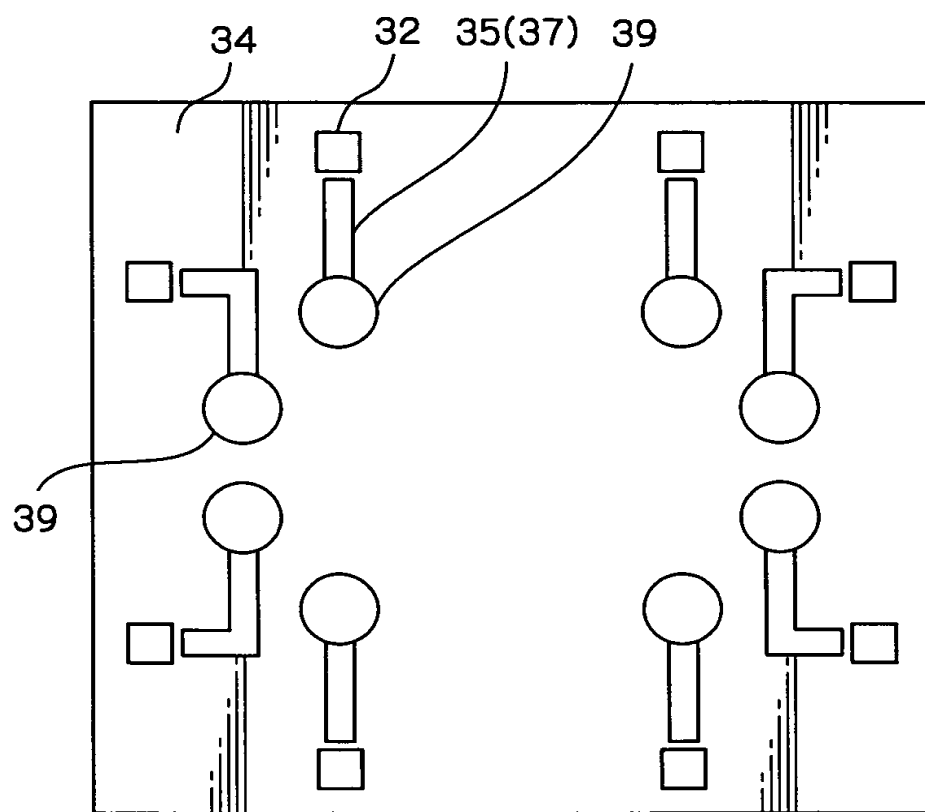


Fig. 8A

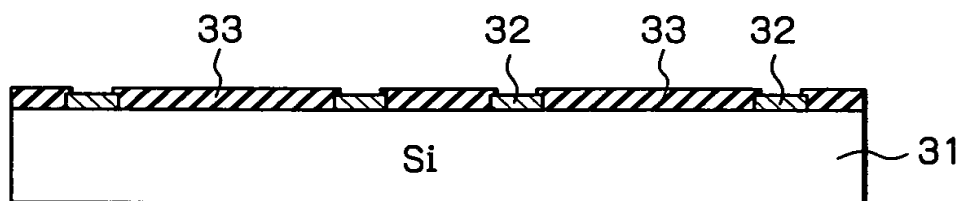


Fig. 8B

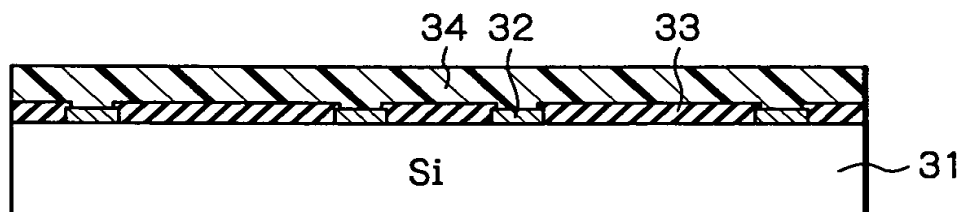


Fig. 8C

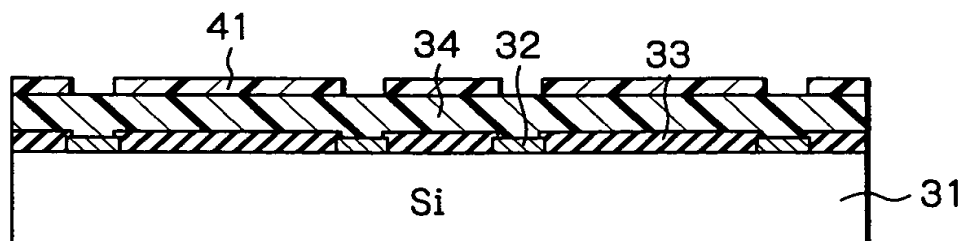


Fig. 8D

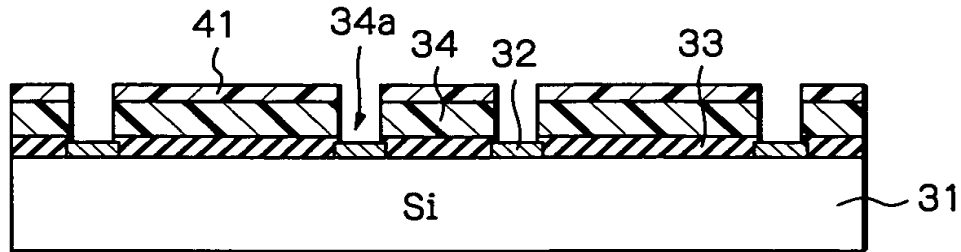


Fig. 8E

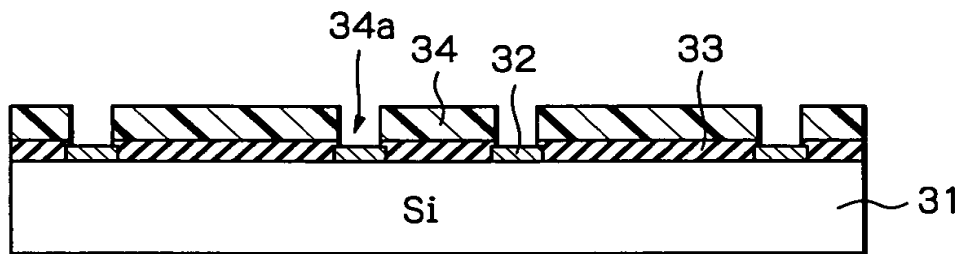


Fig. 8F

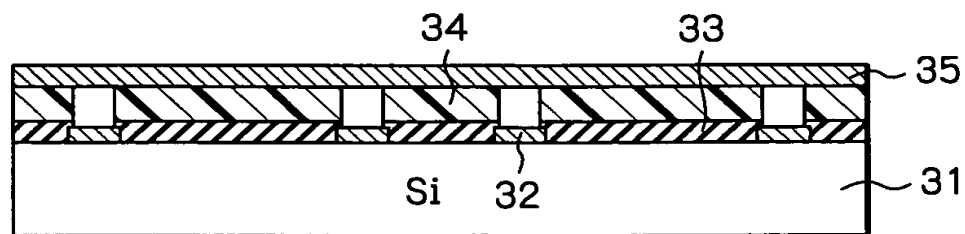


Fig. 8G

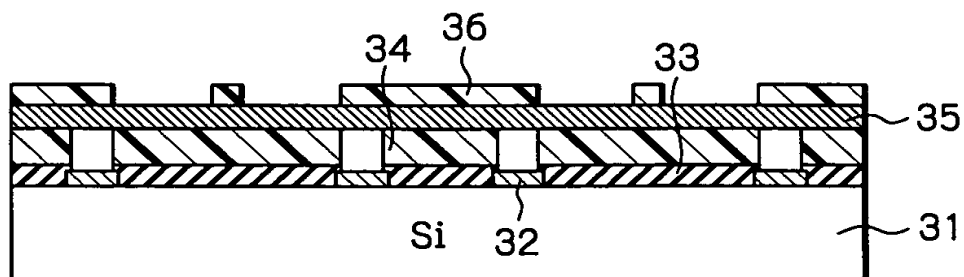


Fig. 8H

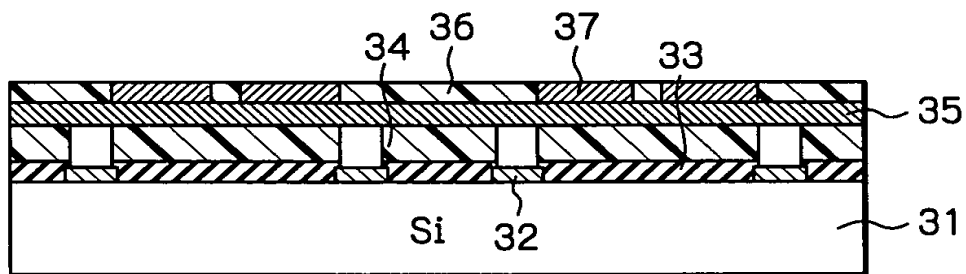


Fig. 8I

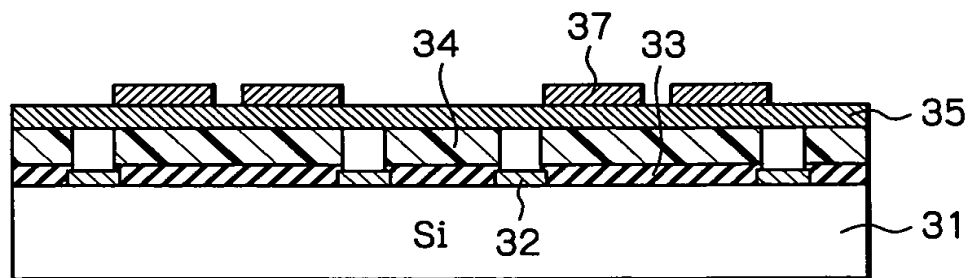


Fig. 8J

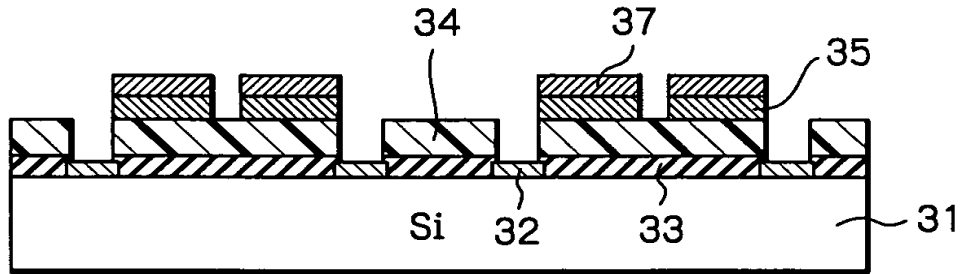


Fig. 8K

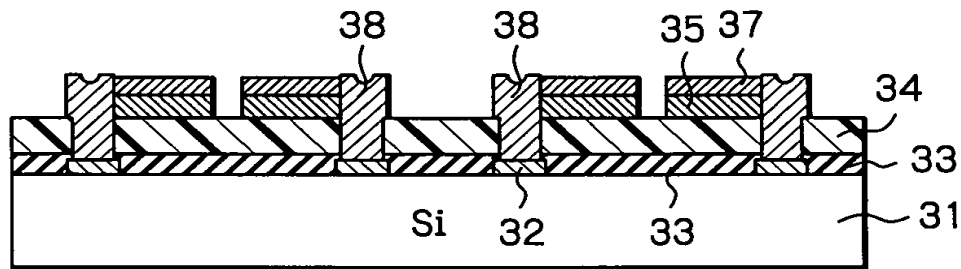
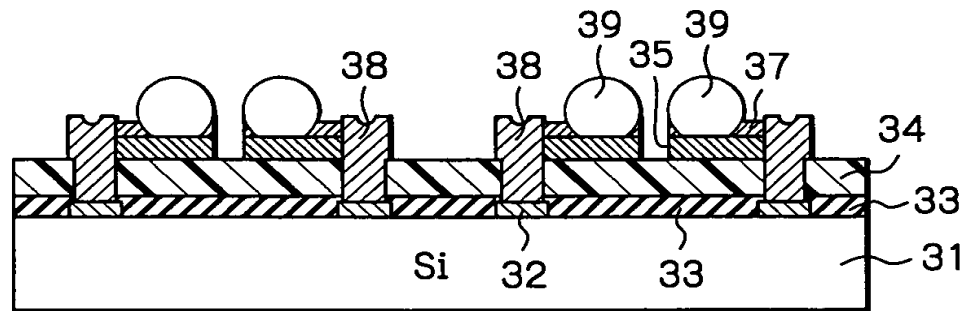


Fig. 8L



Inventor(s): Hirokazu HONDA
DOCKET NO.: 067123-0195

$$\frac{20}{37}$$

Fig. 8M

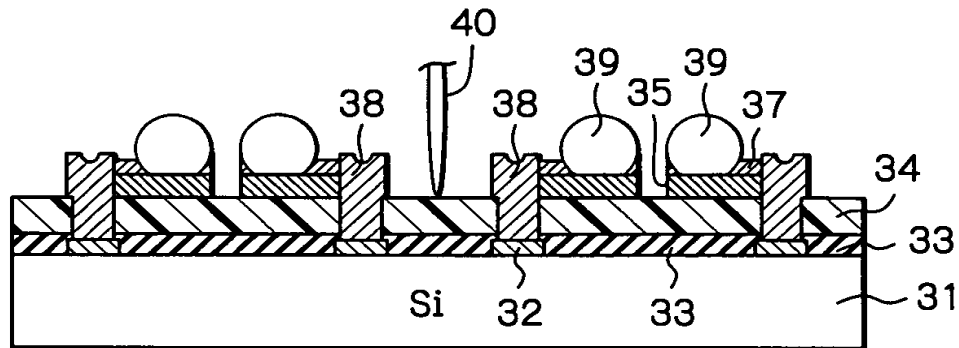


Fig. 8N

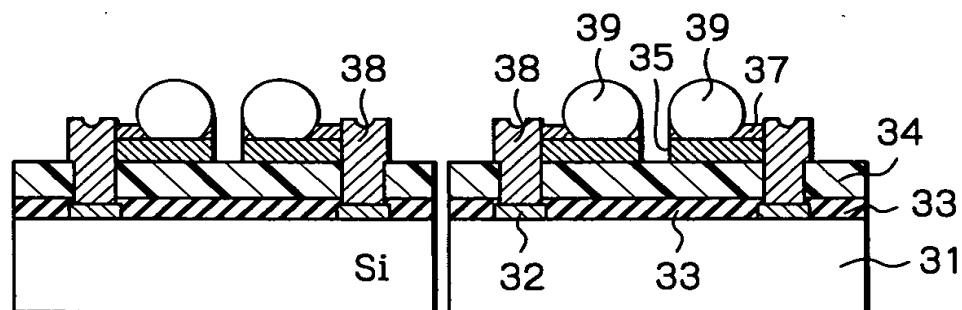


Fig. 9A

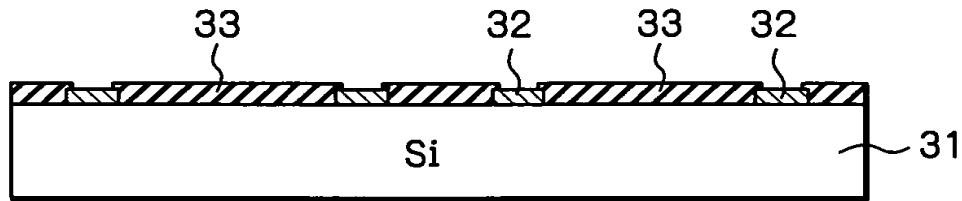


Fig. 9B

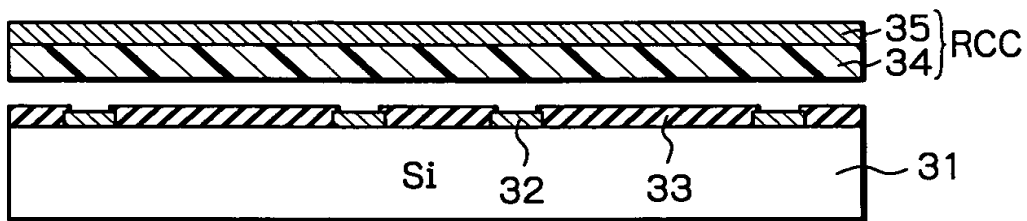


Fig. 9C

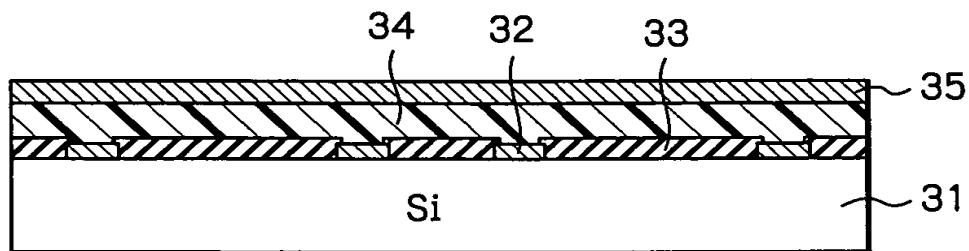


Fig. 10A

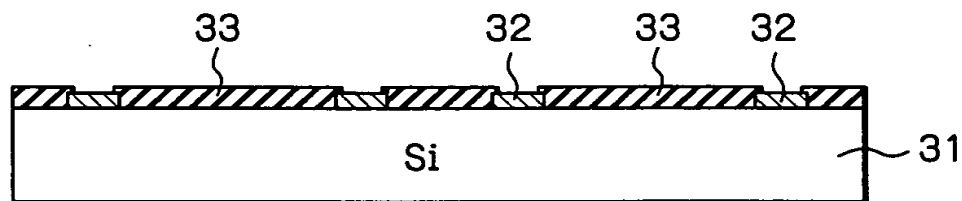


Fig. 10B

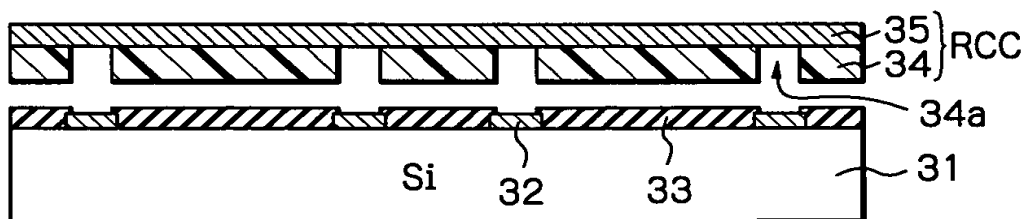
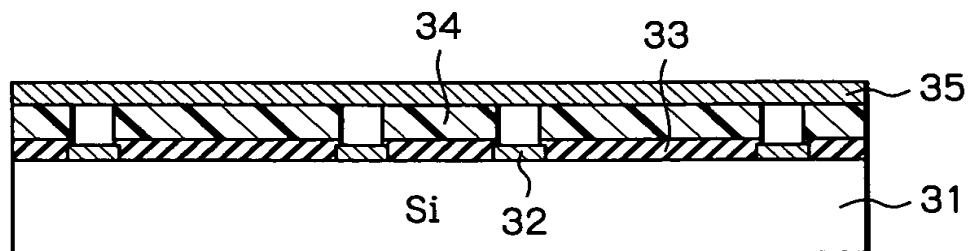


Fig. 10C



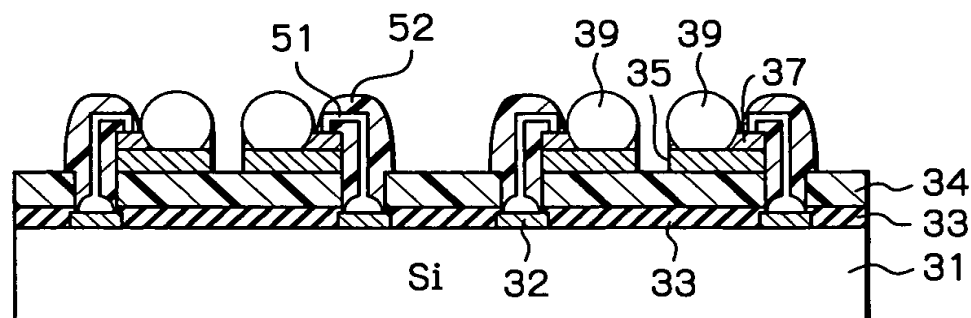


Fig. 11D

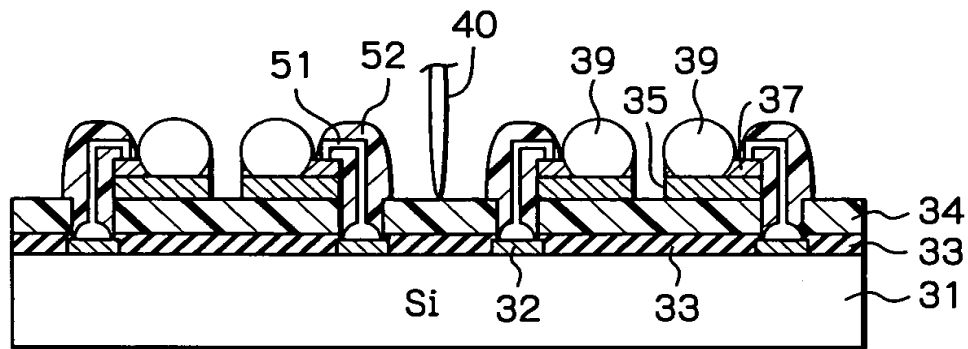


Fig. 11E

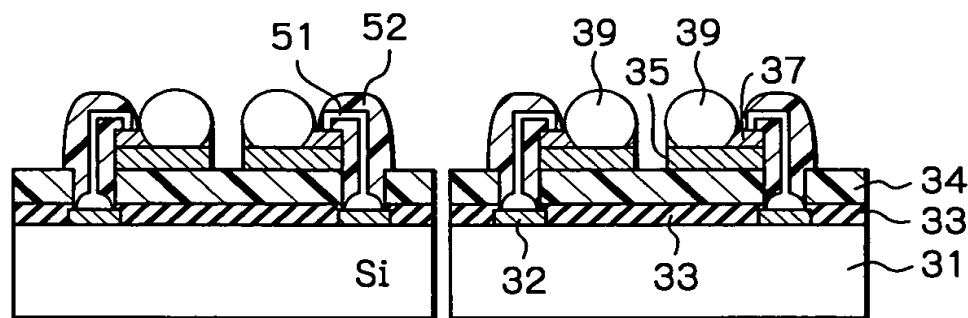


Fig. 12A

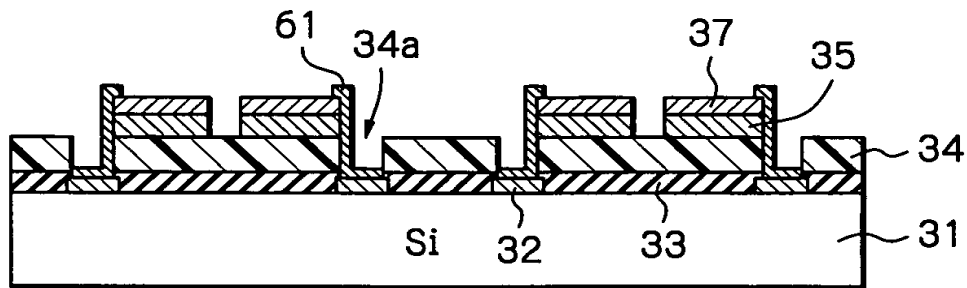


Fig. 12B

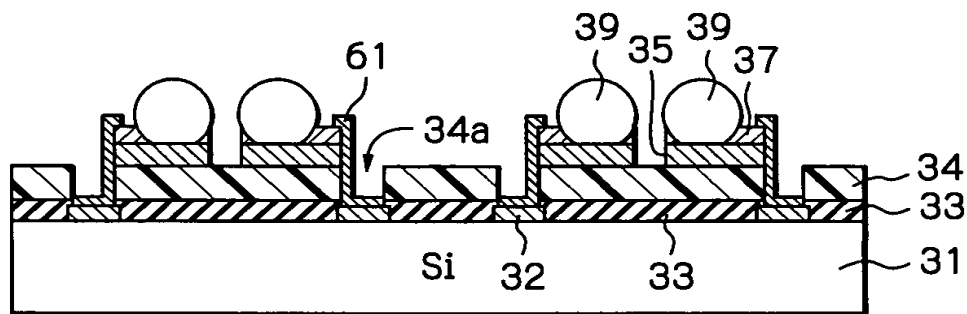


Fig. 12C

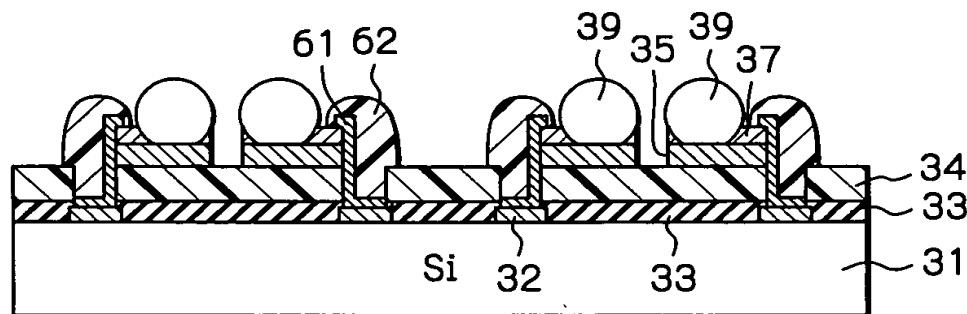


Fig. 12D

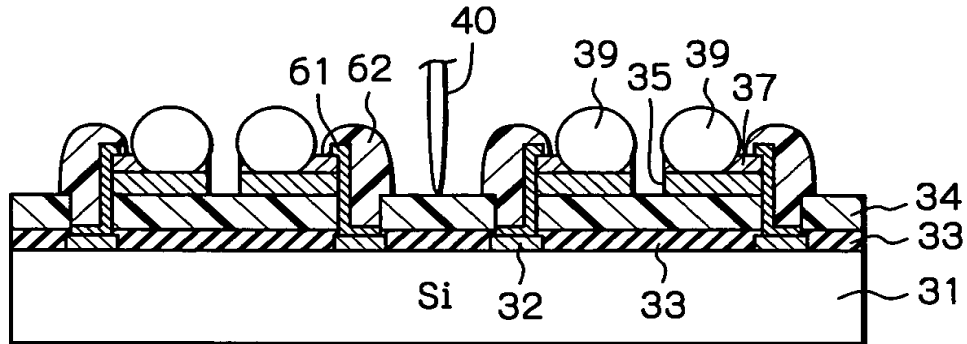


Fig. 12E

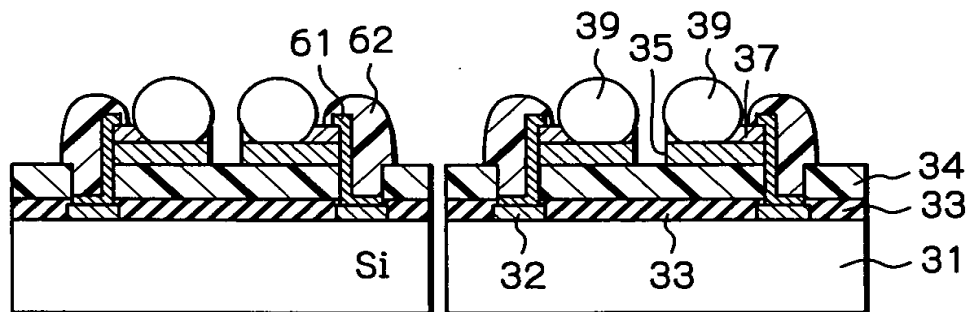


Fig. 13A

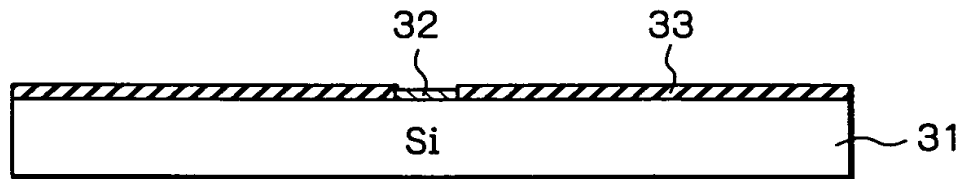


Fig. 13B

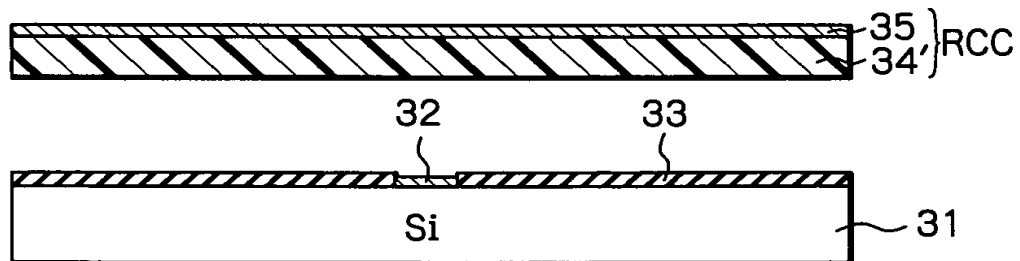


Fig. 13C

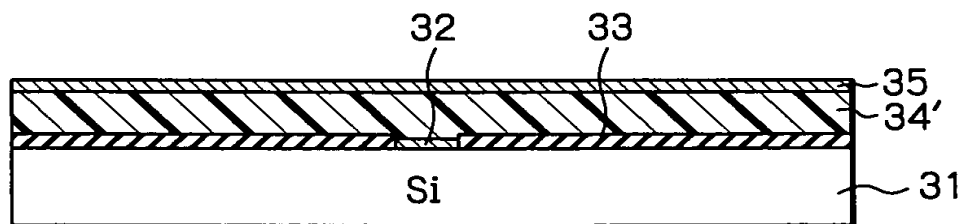


Fig. 13D

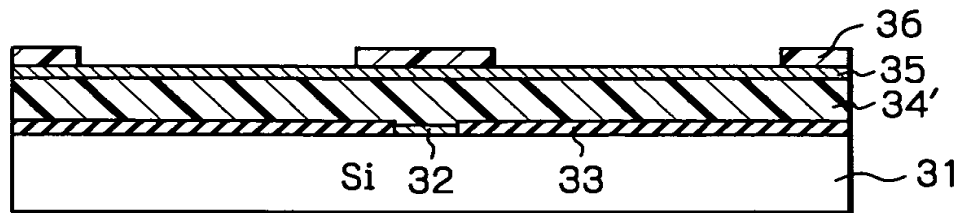


Fig. 13E

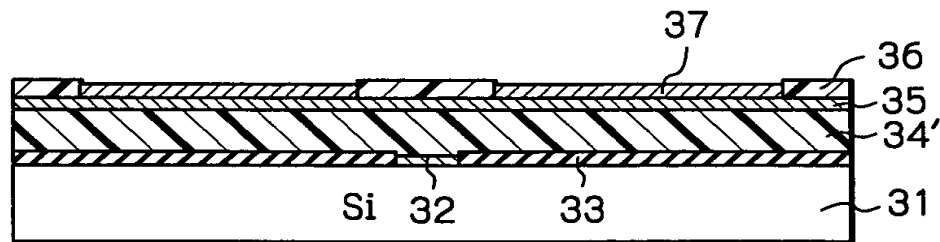


Fig. 13F

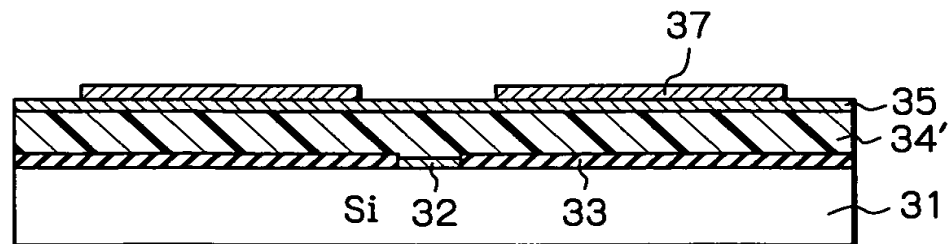


Fig. 13G

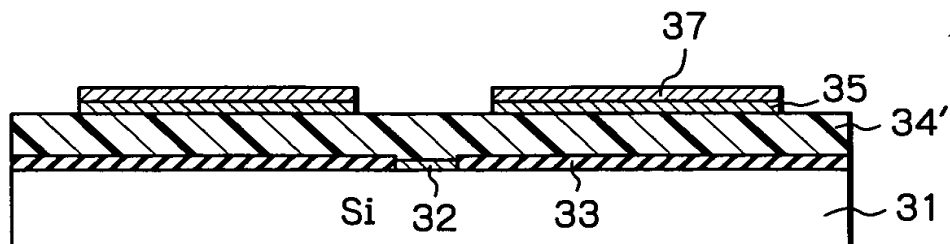


Fig. 13H

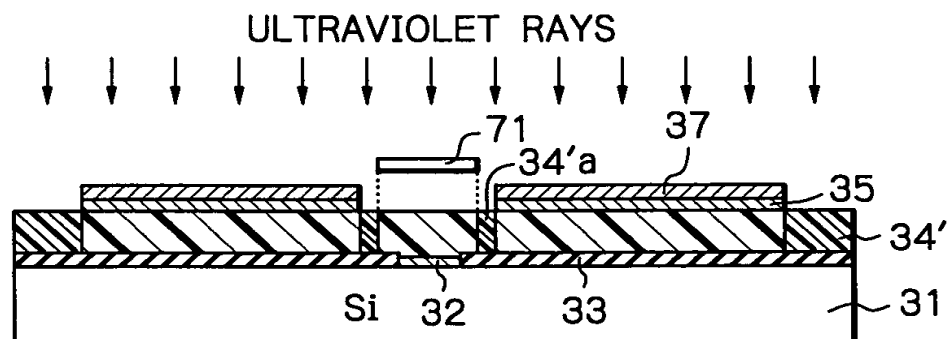


Fig. 13I

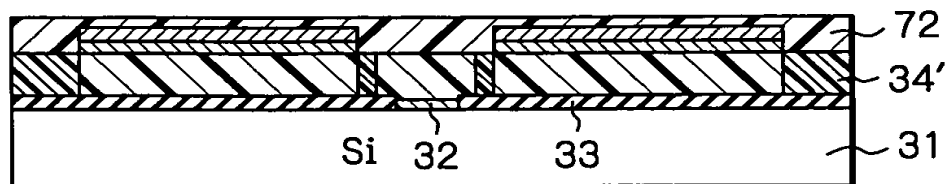


Fig. 13J

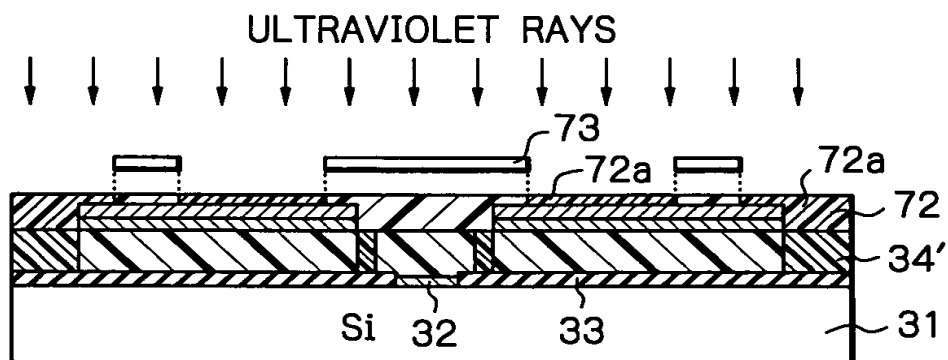


Fig. 13K

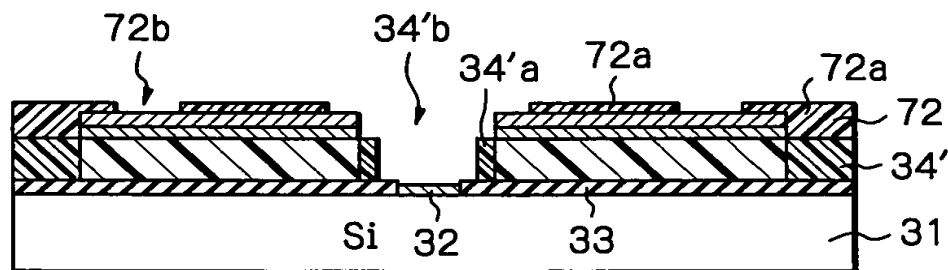


Fig. 13L

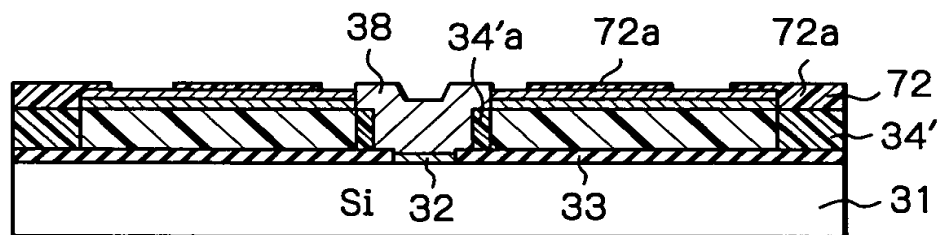


Fig. 13M

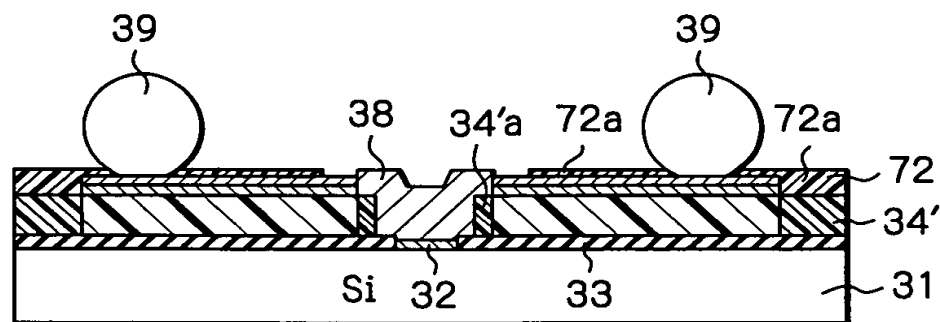


Fig. 14A

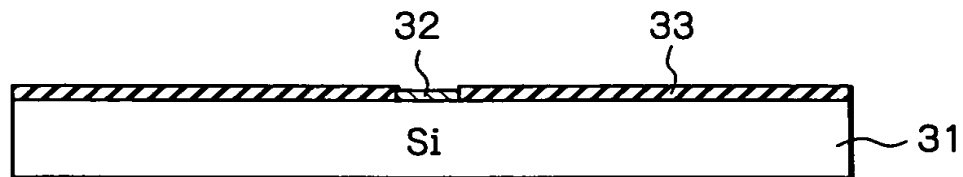


Fig. 14B

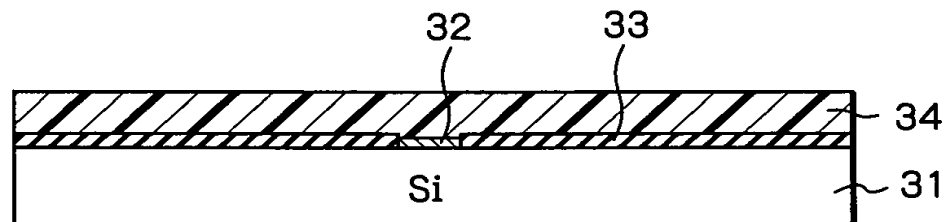


Fig. 14C

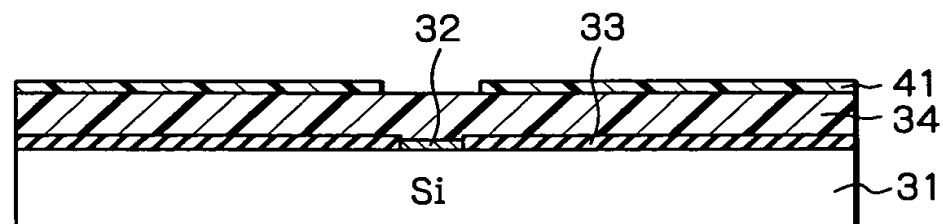


Fig. 14D

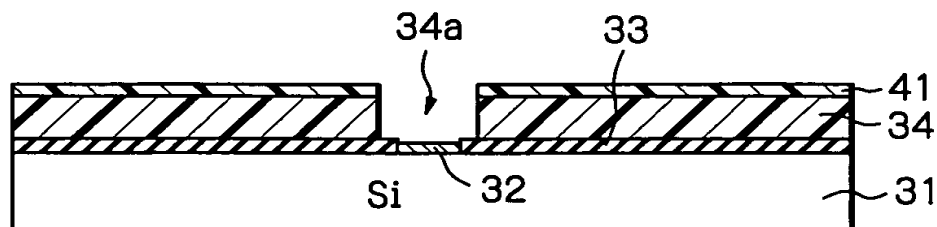


Fig. 14E

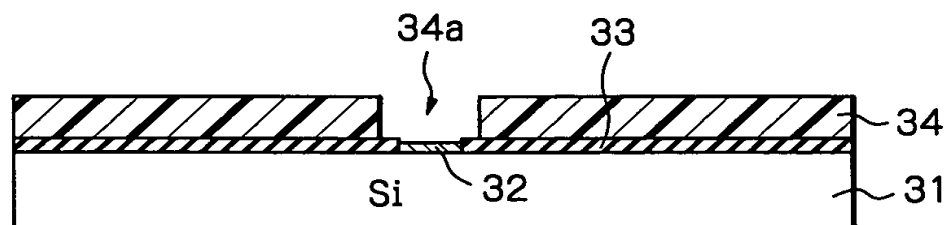


Fig. 14F

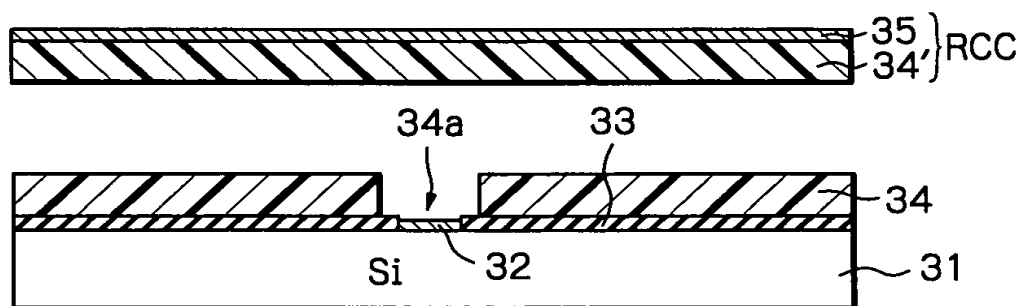


Fig. 14G

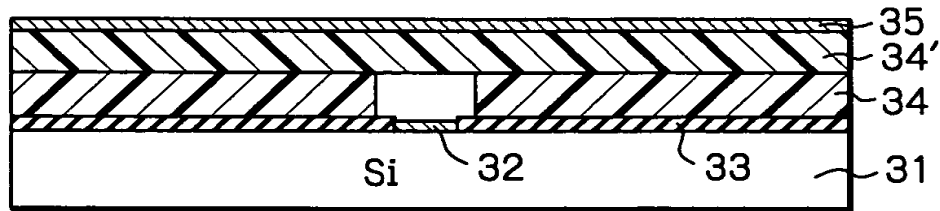


Fig. 14H

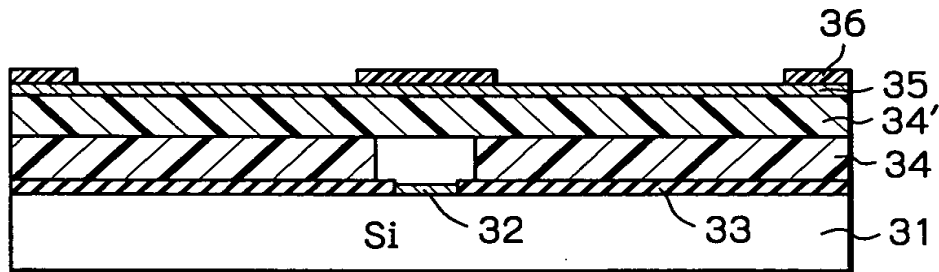
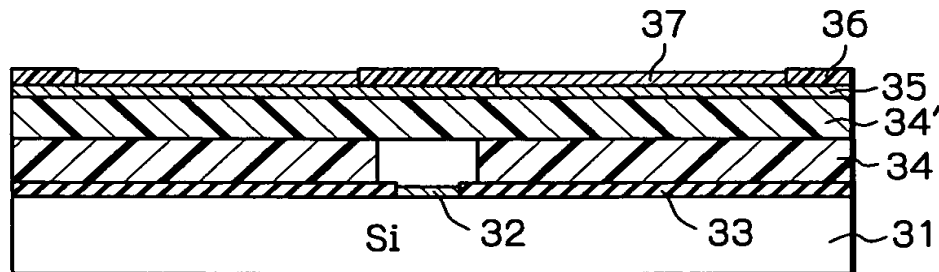


Fig. 14I



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37

Fig. 14J

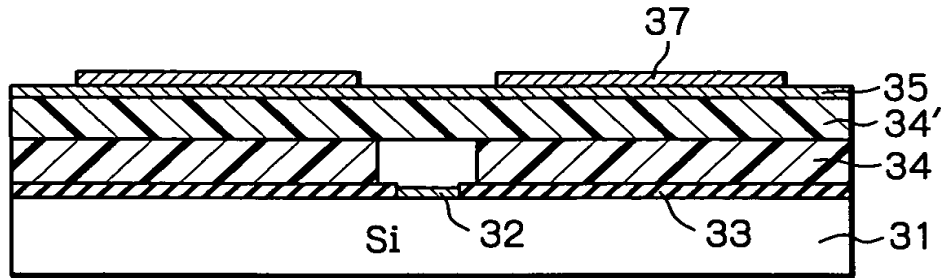


Fig. 14K

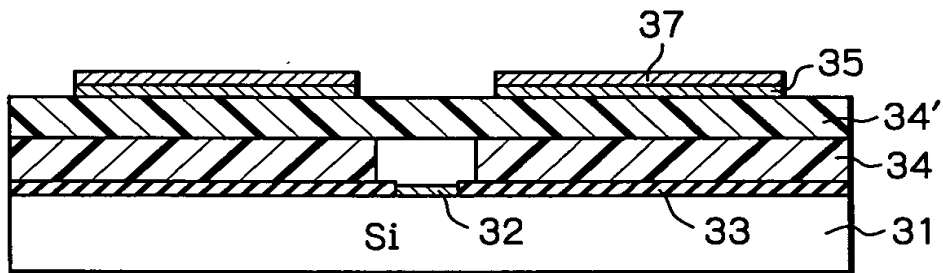


Fig. 14L

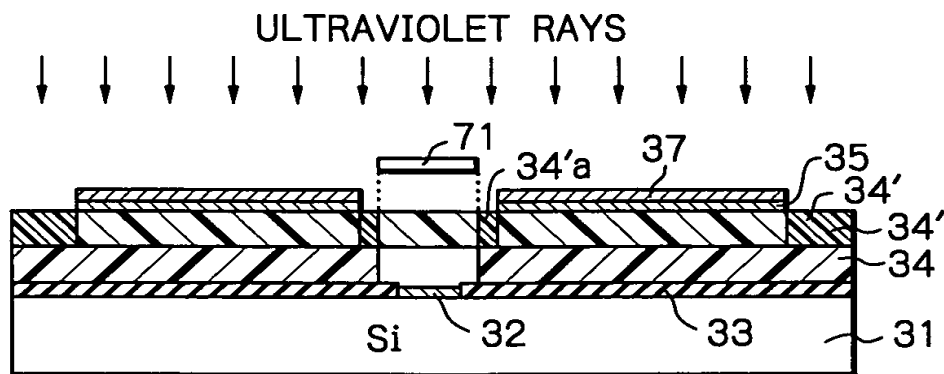


Fig. 14M

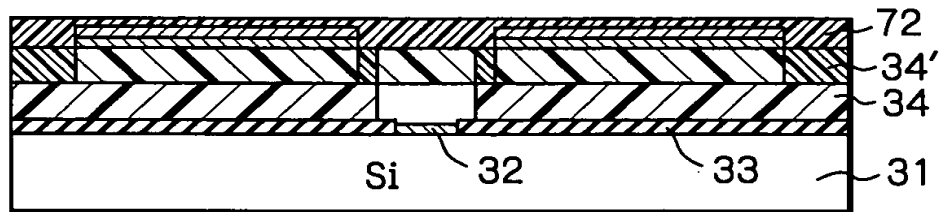


Fig. 14N

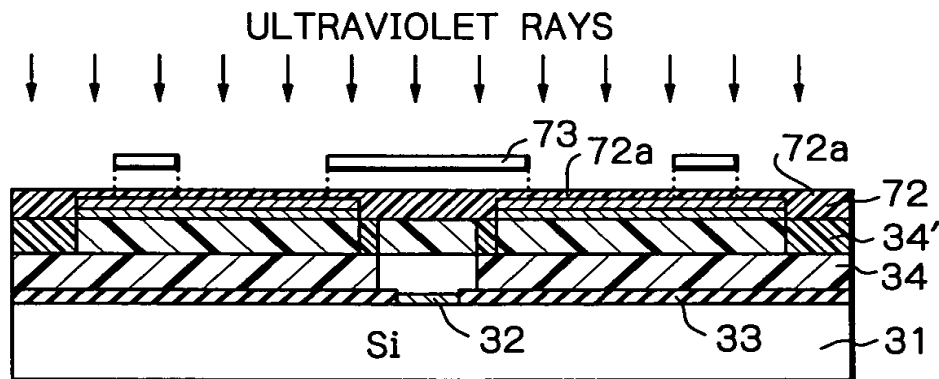


Fig. 14O

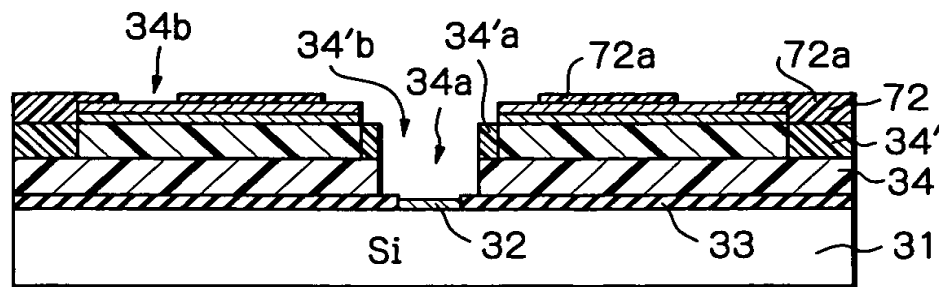


Fig. 14P

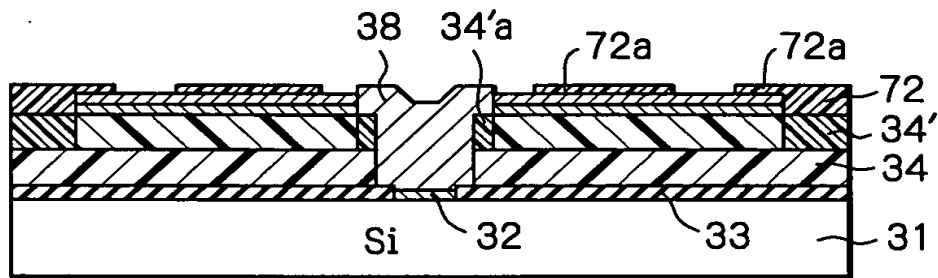


Fig. 14Q

